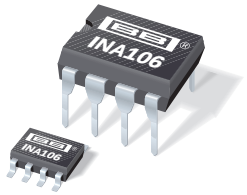
INA106



SBOS152A – AUGUST 1987 – REVISED OCTOBER 2003

Precision Gain = 10 DIFFERENTIAL AMPLIFIER

FEATURES

- ACCURATE GAIN: ±0.025% max
- HIGH COMMON-MODE REJECTION: 86dB min
- NONLINEARITY: 0.001% max
- EASY TO USE
- PLASTIC 8-PIN DIP, SO-8 SOIC PACKAGES

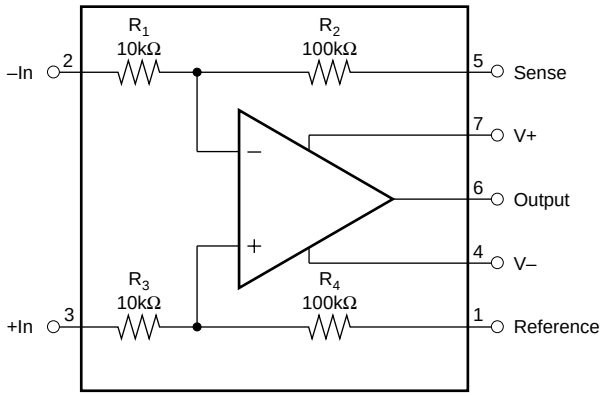
APPLICATIONS

- G = 10 DIFFERENTIAL AMPLIFIER
- G = +10 AMPLIFIER
- G = –10 AMPLIFIER
- G = +11 AMPLIFIER
- INSTRUMENTATION AMPLIFIER

DESCRIPTION

The INA106 is a monolithic Gain = 10 differential amplifier consisting of a precision op amp and on-chip metal film resistors. The resistors are laser trimmed for accurate gain and high common-mode rejection. Excellent TCR tracking of the resistors maintains gain accuracy and common-mode rejection over temperature.

The differential amplifier is the foundation of many commonly used circuits. The INA106 provides this precision circuit function without using an expensive resistor network. The INA106 is available in 8-pin plastic DIP and SO-8 surface-mount packages.



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SPECIFICATIONS

ELECTRICAL

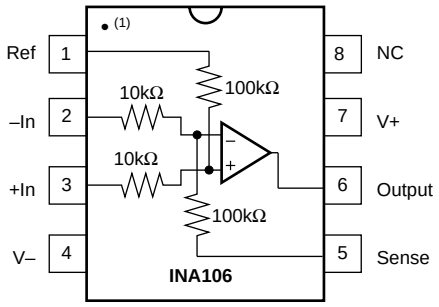
At +25°C, V_S = ±15V, unless otherwise specified.

PARAMETER	CONDITIONS	INA106KP, U			UNITS
		MIN	TYP	MAX	
GAIN					
Initial[1]			10		V/V
Error			0.01	0.025	%
vs Temperature			–4		ppm/°C
Nonlinearity[2]			0.0002	0.001	%
OUTPUT					
Related Voltage	I_O = +20mA, –5mA	10	12		V
Rated Current	V_O = 10V	+20, –5			mA
Impedance			0.01		Ω
Current Limit	To Common		+40/–10		mA
Capacitive Load	Stable Operation		1000		pF
INPUT					
Impedance	Differential		10		kΩ
	Common-Mode		110		kΩ
Voltage Range	Differential	±1			V
	Common-Mode	±11			V
Common-Mode Rejection[3]	$T_A = T_{MIN}$ to T_{MAX}	86	100		dB
OFFSET VOLTAGE	RTI[4]				
Initial			50	200	µV
vs Temperature			0.2		µV/°C
vs Supply	$\pm V_S$ = 6V to 18V		1	10	µV/V
vs Time			10		µV/mo
NOISE VOLTAGE	RTI[5]				
f_B = 0.01Hz to 10Hz			1		µVp-p
f_O = 10kHz			30		nV/√Hz
DYNAMIC RESPONSE					
Small Signal	–3dB		5		MHz
Full Power BW	V_O = 20Vp-p	30	50		kHz
Slew Rate		2	3		V/µs
Settling Time: 0.1%	V_O = 10V Step		5		µs
0.01%	V_O = 10V Step		10		µs
0.01%	V_{CM} = 10V Step, V_{DIFF} = 0V		5		µs
POWER SUPPLY					
Rated			±15		V
Voltage Range	Derated Performance	±5		±18	V
Quiescent Current	V_O = 0V		±1.5	±2	mA
TEMPERATURE RANGE					
Specification		0		+70	°C
Operation		–40		+85	°C
Storage		–65		+150	°C

NOTES: (1) Connected as difference amplifier (see Figure 1). (2) Nonlinearity is the maximum peak deviation from the best-fit straight line as a percent of full-scale peak-to-peak output. (3) With zero source impedance (see "Maintaining CMR" section). (4) Includes effects of amplifiers's input bias and offset currents. (5) Includes effect of amplifier's input current noise and thermal noise contribution of resistor network.

PIN CONFIGURATION

Top View **DIP/SOIC**



NOTE: (1) Pin 1 indentifier for SO-8 package. Model number identification may be abbreviated on SO-8 package due to limited available space.

ABSOLUTE MAXIMUM RATINGS

Power Supply Voltage	±18V
Input Voltage Range	$\pm V_S$
Operating Temperature Range: P, U	–40°C to +85°C
Storage Temperature Range	–40°C to +85°C
Lead Temperature (soldering, 10s): P	+300°C
Wave Soldering (3s, max) U	+260°C
Output Short Circuit to Common	Continuous

NOTE: (1) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

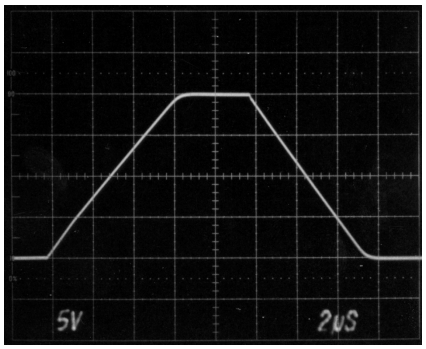
PACKAGE/ORDERING INFORMATION

For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.

TYPICAL PERFORMANCE CURVES

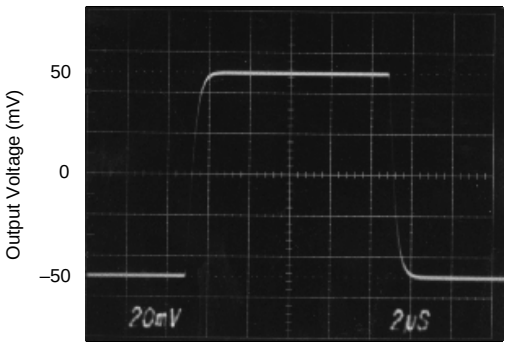
At T_A = +25°C, V_S = ±15V, unless otherwise noted.

STEP RESPONSE



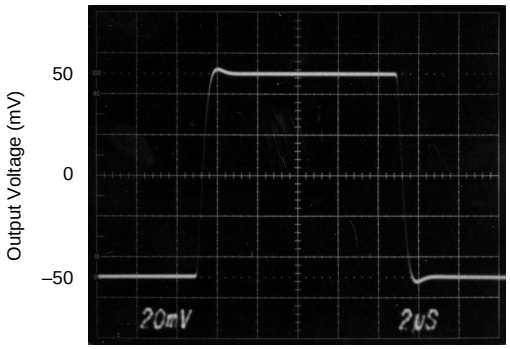
2µs/div

SMALL SIGNAL RESPONSE
(No Load)



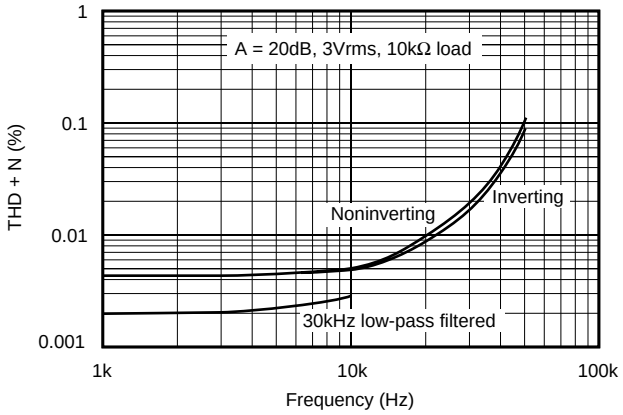
2µs/div

SMALL SIGNAL RESPONSE
(R_{LOAD} = ∞, C_{LOAD} = 100pF)

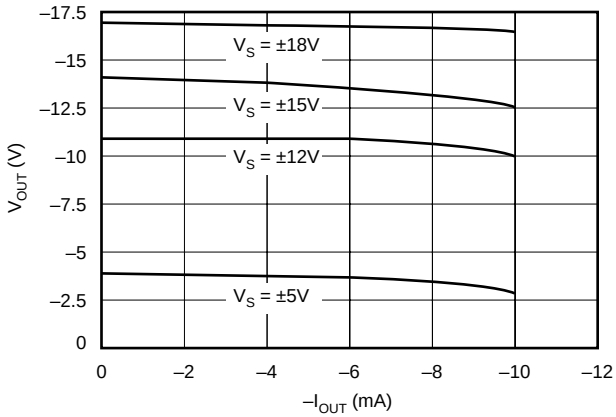


2µs/div

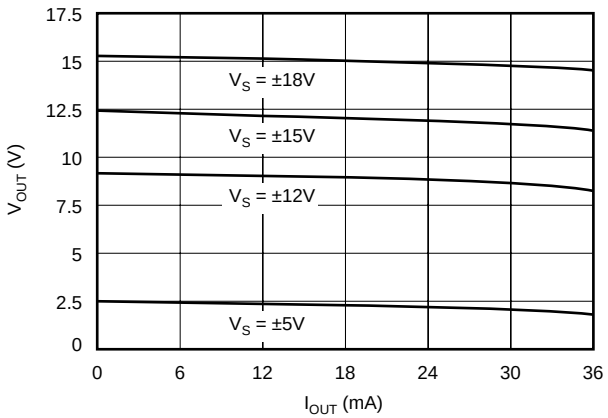
TOTAL HARMONIC DISTORTION AND NOISE
vs FREQUENCY



MAXIMUM V_{OUT} vs I_{OUT}
(Negative Swing)

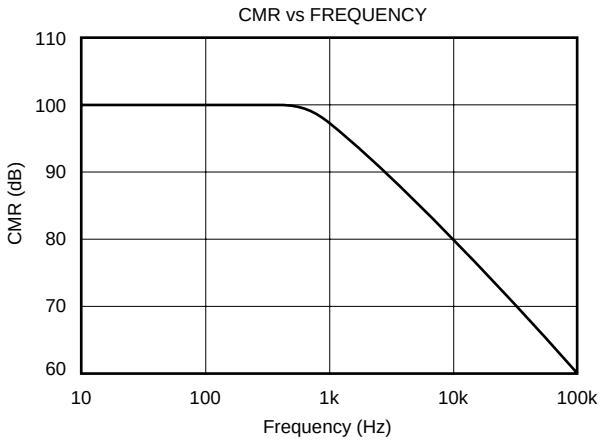


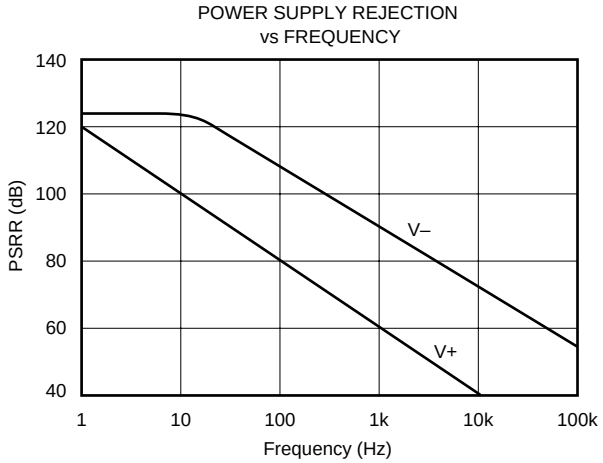
MAXIMUM V_{OUT} vs I_{OUT}
(Positive Swing)



TYPICAL PERFORMANCE CURVES (CONT)

At T_A = +25°C, V_S = ±15V, unless otherwise noted.





APPLICATIONS INFORMATION

Figure 1 shows the basic connections required for operation of the INA106. Power supply bypass capacitors should be connected close to the device pins as shown.

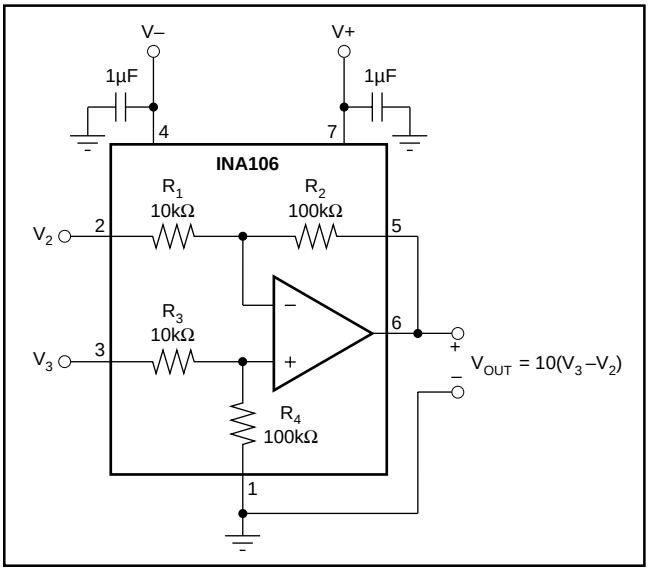


FIGURE 1. Basic Power Supply and Signal Connections.

The differential input signal is connected to pins 2 and 3 as shown. The source impedance connected to the inputs must be equal to assure good common-mode rejection. A 5Ω mismatch in source impedance will degrade the common-mode rejection of a typical device to approximately 86dB. If the source has a known source impedance mismatch, an additional resistor in series with one input can be used to preserve good common-mode rejection.

The output is referred to the output reference terminal (pin 1) which is normally grounded. A voltage applied to the Ref terminal will be summed with the output signal. The source impedance of a signal applied to the Ref terminal should be less than 10Ω to maintain good common-mode rejection.

Figure 2 shows a voltage applied to pin 1 to trim the offset voltage of the INA106. The known 100Ω source impedance of the trim circuit is compensated by the 10Ω resistor in series with pin 3 to maintain good CMR.

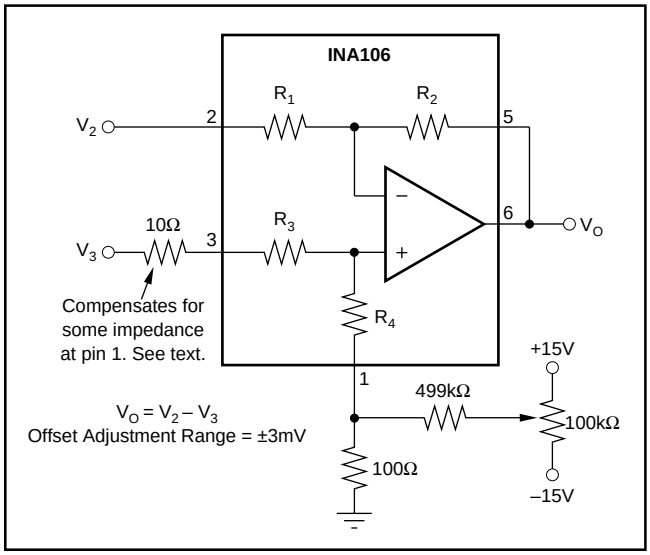


FIGURE 2. Offset Adjustment.

Referring to Figure 1, the CMR depends upon the match of the internal R_4/R_3 ratio to the R_1/R_2 ratio. A CMR of 106dB requires resistor matching of 0.005%. To maintain high CMR over temperature, the resistor TCR tracking must be better than 2ppm/°C. These accuracies are difficult and expensive to reliably achieve with discrete components.

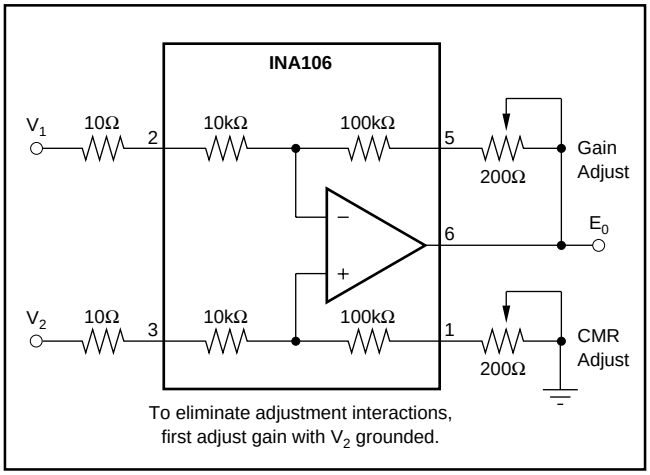


FIGURE 3. Difference Amplifier with Gain and CMR Adjust.

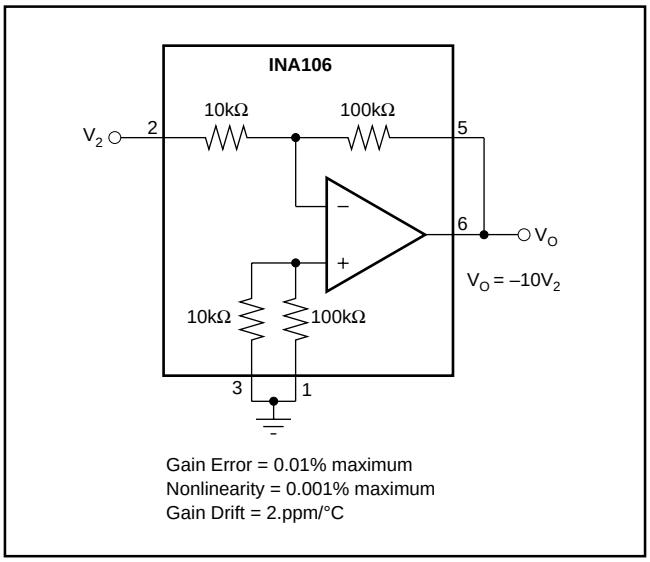


FIGURE 4. Precision G = –10 Inverting Amplifier.

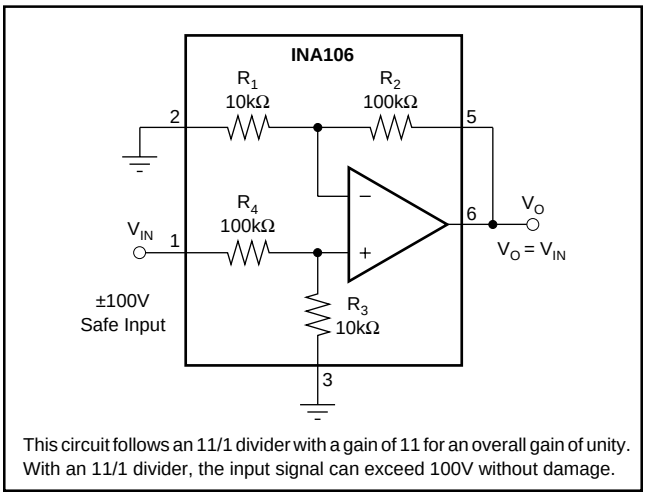
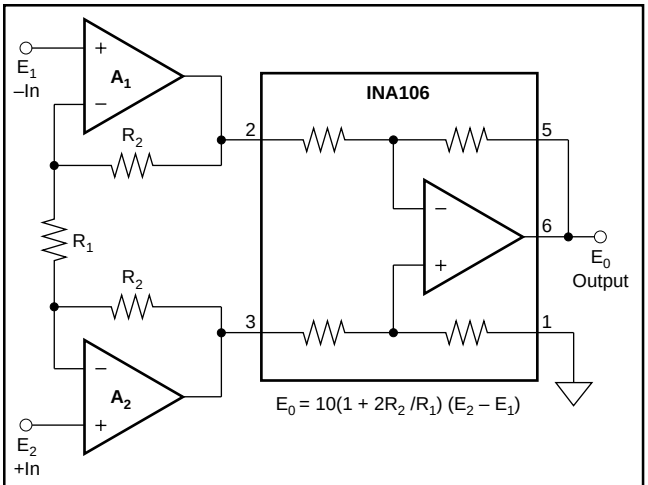


FIGURE 5. Voltage Follower with Input Protection.



To make a high performance high gain instrumentation amplifier, the INA106 can be combined with state-of-the-art op amps. For low source impedance applications, OPA37s will give the best noise, offset, and temperature drift. At source impedances above about 10kΩ, the bias current noise of the OPA37 reacting with input impedance degrades noise. For these applications, use an OPA111 or a dual OPA2111 FET input op amp for lower noise. For an electrometer grade IA, use the OPA128—see table below.

Using the INA106 for the difference amplifier also extends the input common-mode range of the instrumentation amplifier to ±10V. A conventional IA with a unity-gain difference amplifier has an input common-mode range limited to ±5V for an output swing of ±10V. This is because a unity-gain difference amp needs ±5V at the input for 10V at the output, allowing only 5V additional for common-mode.

A_1, A_2	R_1 (Ω)	R_2 (kΩ)	GAIN (V/V)	CMRR (dB)	I_b (pA)	NOISE AT 1kHz (nV/ $\sqrt{Hz}$)
OPA37A	50.5	2.5	1000	128	40000	4
OPA111B	202	10	1000	110	1	10
OPA128LM	202	10	1000	118	0.075	38

FIGURE 6. Precision Instrumentation Amplifier.

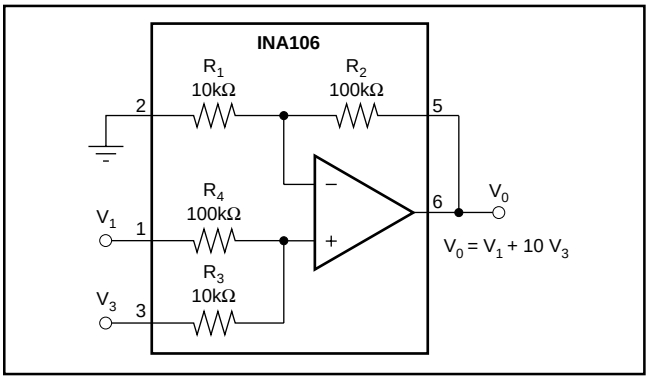


FIGURE 7. Precision Summing Amplifier.

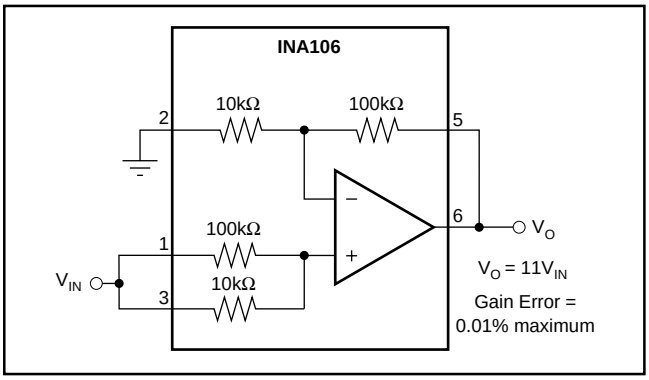


FIGURE 8. Precision G = 11 Buffer.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
INA106KP	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
INA106KPG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
INA106U	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
INA106U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
INA106U/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
INA106UE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

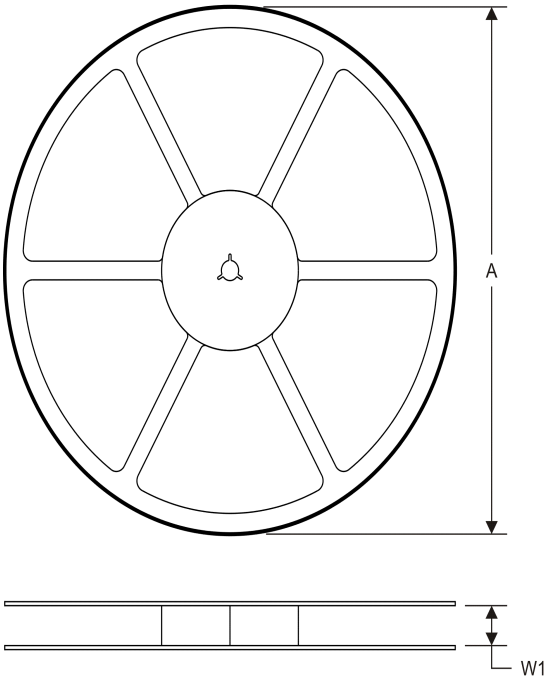
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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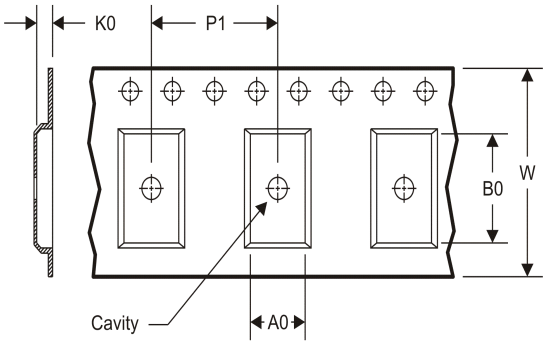
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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



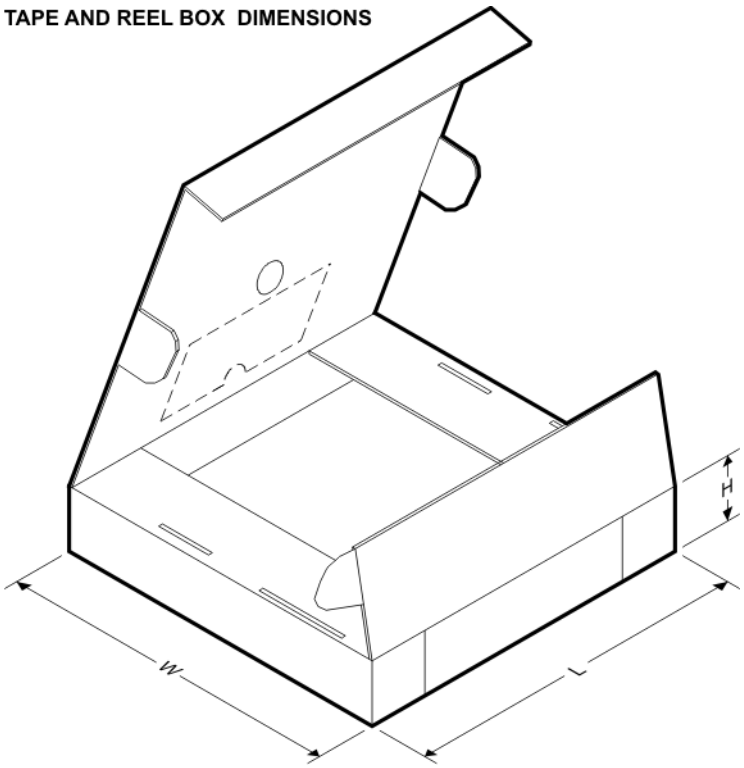
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA106U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

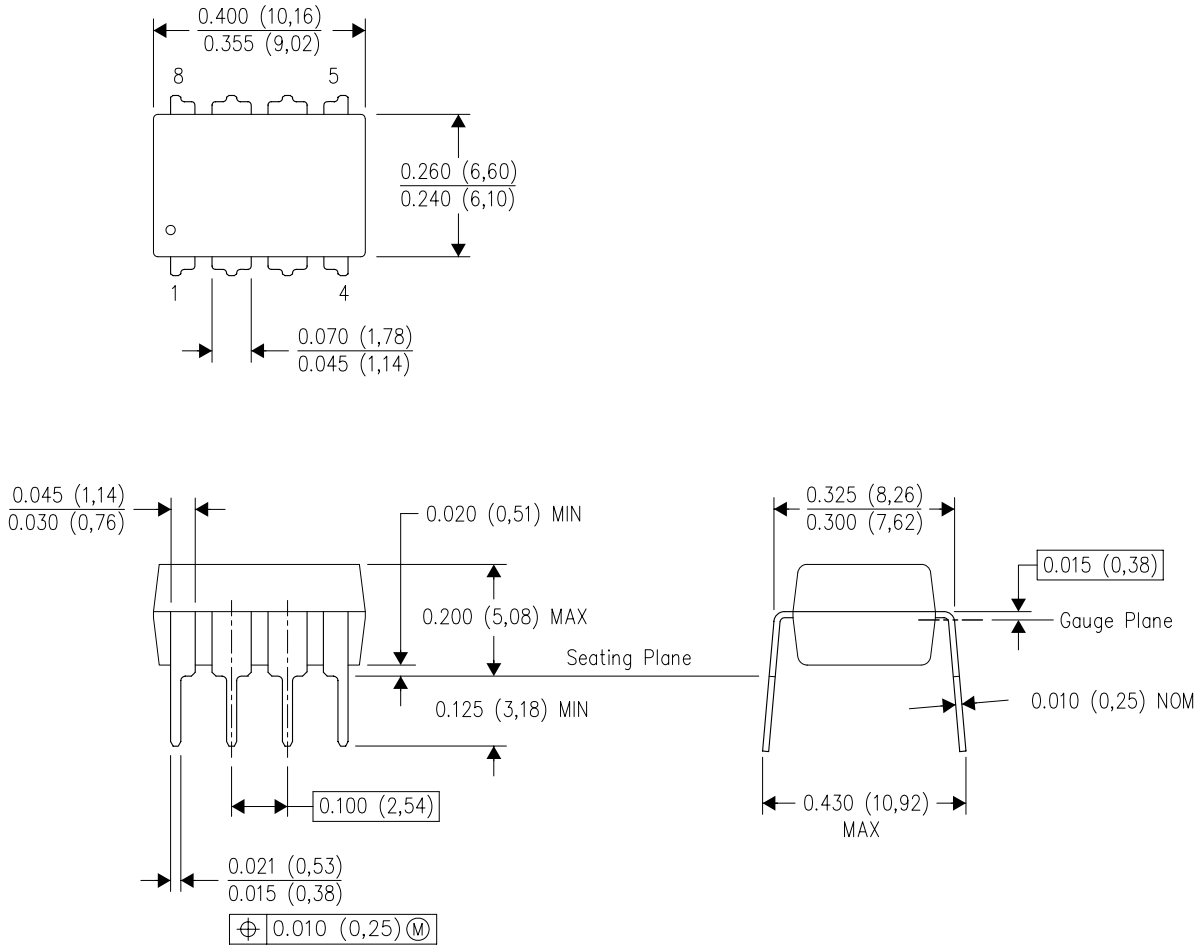
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

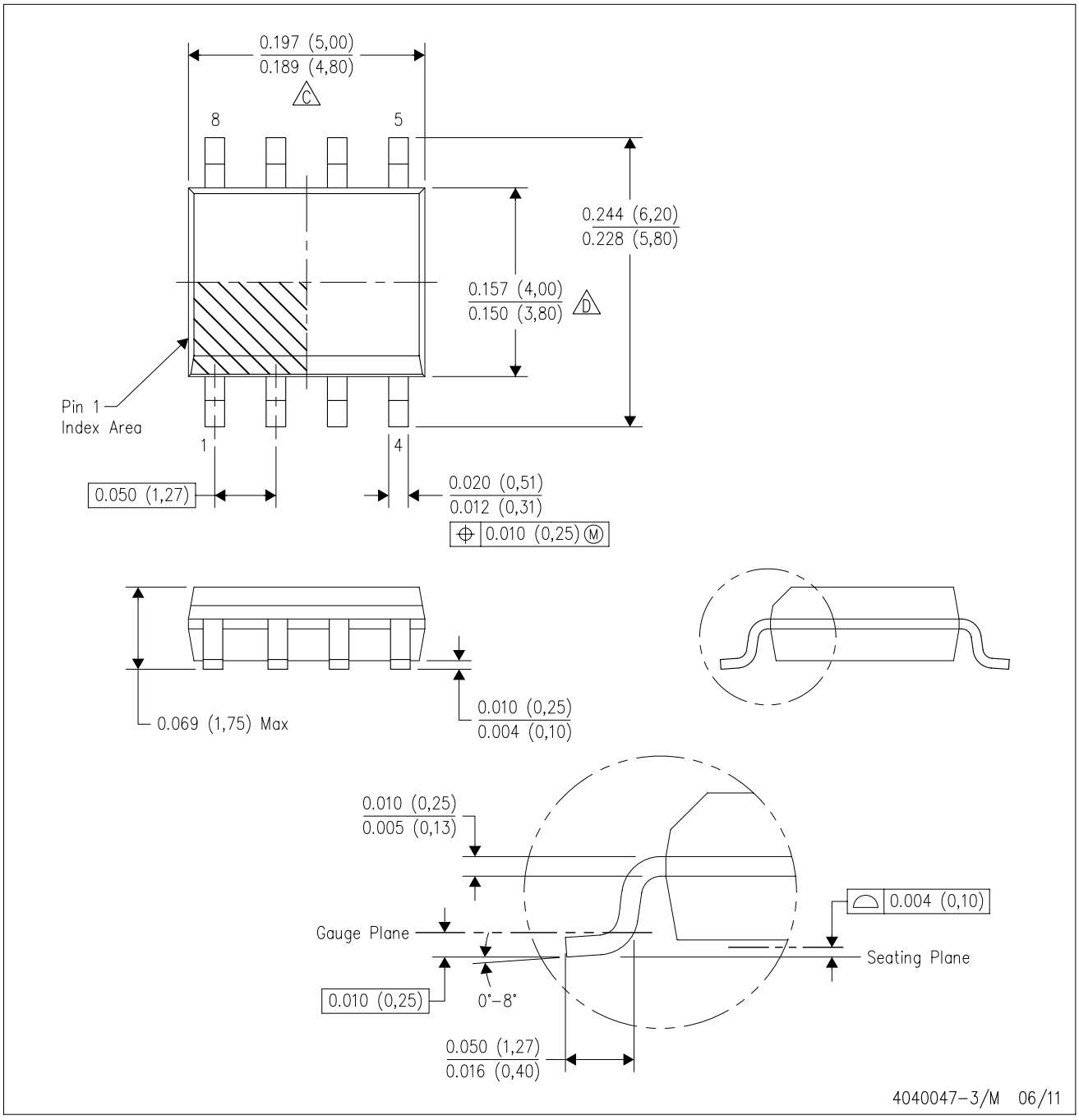
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA106U/2K5	SOIC	D	8	2500	367.0	367.0	35.0

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



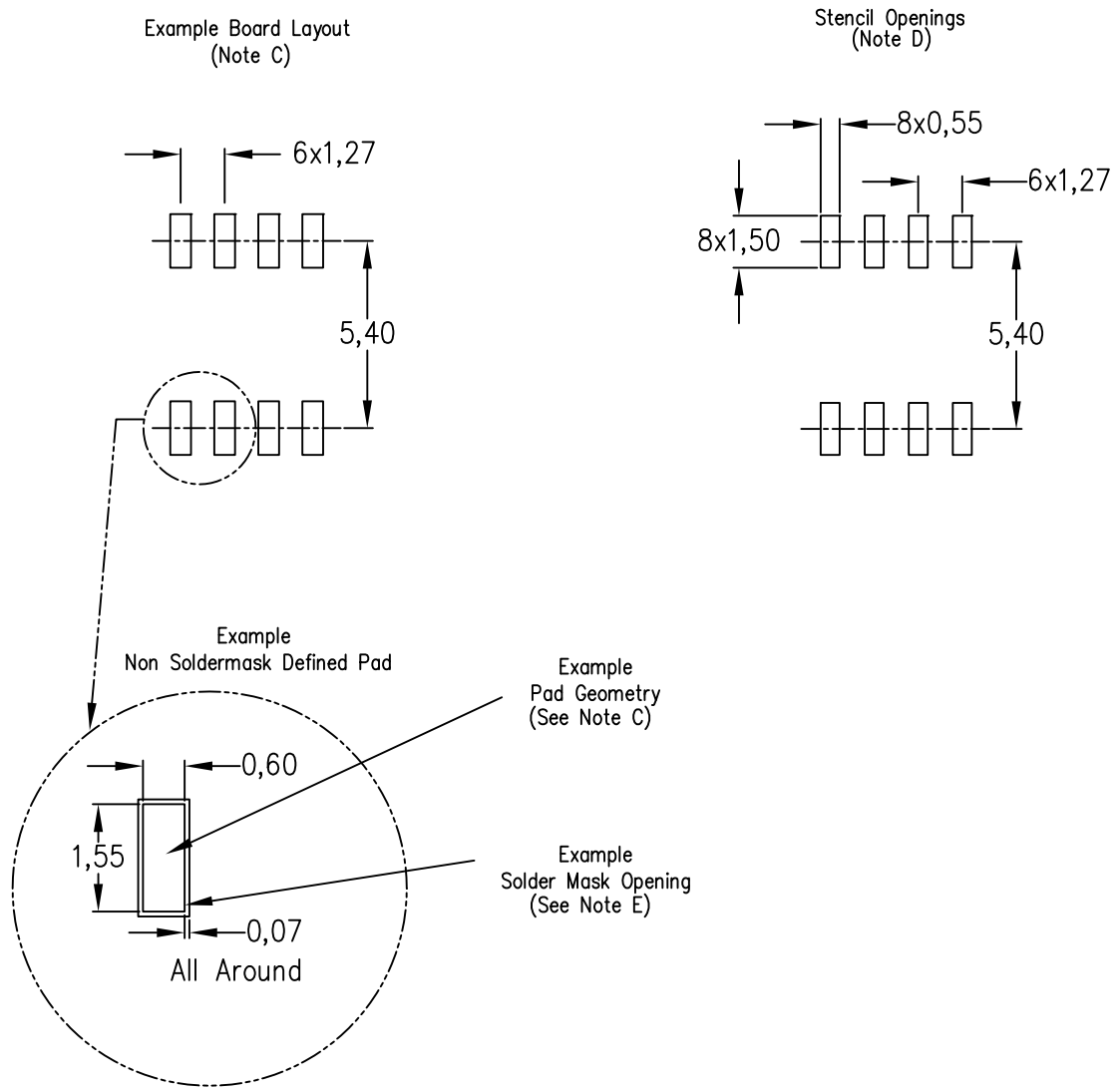
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AA.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

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